

Appl. No. 10/711,369
Amtd. dated October 24, 2005
Reply to Office action of July 27, 2005

Amendments to the Claims:

Claims 1-10, 20 (previously withdrawn from consideration) are canceled herewith.

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-10, 20 are cancelled.

11. (currently amended) A slurry for performing chemical mechanical polishing (CMP) of [[a]] oxides on a substrate, comprising:
ceria particles having a first concentration; and
silica particles having a second concentration;
wherein:
the concentration of ceria in the slurry is approximately 1.0 - 5.0 wt%; and
the concentration of silica in the slurry is approximately 0.1 - 5.0 wt%.
12. (original) The slurry of claim 11, wherein a ratio of ceria concentration to silica concentration (ceria:silica) is from approximately 10:1 to nearly 1:1 by weight.
13. (original) The slurry of claim 12, wherein the ratio of ceria:silica is selected from the group consisting of from 10:1 to 7:1, from 10:1 to 4:1, from 10:1 to 1.1:1, approximately 10:1, approximately 7:1, approximately 4:1, greater than 1:1, greater than 4:1, and greater than 7:1.
14. (original) The slurry of claim 11, wherein:
the ceria particles have a first particle size and the silica particles have a second particle size; and
a ratio of first particle size to second particle size (ceria:silica) is selected from the group consisting of approximately 1:1, approximately 1.5:1, approximately 2:1, and approximately 2.5:1.
15. (currently amended) The slurry of claim 11, wherein:
the ceria particles have a particle size of 150-250 nm[:]; and
the silica particles have a particle size of > 100 nm.
16. (original) The slurry of claim 15, wherein the ceria particles have a particle size of 180-220 nm.
17. (original) The slurry of claim 15, wherein the silica particles have a particle size of 130-190 nm.
18. (original) The slurry of claim 11, wherein the silica particles comprise fumed silica.

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19. (original) The slurry of claim 11, wherein the slurry has a pH of approximately 9.0.

20. (canceled)

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21. (new) The slurry of claim 11, wherein the slurry has a pH in the range of from 7-12.

22. (new) The slurry of claim 21, wherein the slurry has a pH in the range of from 8.5 to 9.5.

23. (new) A slurry for performing chemical mechanical polishing (CMP) of oxides on a substrate, comprising:

ceria particles having a first concentration; and

silica particles having a second concentration;

wherein:

the concentration of ceria in the slurry is approximately 1.0 - 5.0 wt%;

the concentration of silica in the slurry is approximately 0.1 - 5.0 wt%;

wherein a ratio of ceria concentration to silica concentration (ceria:silica) is from approximately 10:1 to nearly 1:1 by weight;

the ceria particles have a particle size of 150-250 nm; and

the silica particles have a particle size of > 100 nm;

wherein the silica particles comprise fumed silica; and

wherein the slurry has a pH in the range of from 7-12.

24. (new) The slurry of claim 23, wherein the ratio of ceria:silica is selected from the group consisting of from 10:1 to 7:1, from 10:1 to 4:1, from 10:1 to 1.1:1, approximately 10:1, approximately 7:1, approximately 4:1, greater than 1:1, greater than 4:1, and greater than 7:1.

25. (new) The slurry of claim 23, wherein:

the ceria particles have a first particle size and the silica particles have a second particle size; and

a ratio of first particle size to second particle size (ceria:silica) is selected from the group consisting of approximately 1:1, approximately 1.5:1, approximately 2:1, and approximately 2.5:1.

26. (new) The slurry of claim 23, wherein:

the ceria particles have a particle size of 180-220 nm; and

the silica particles have a particle size of 130-190 nm.

27. (new) The slurry of claim 23, wherein the slurry has a pH of approximately 9.0.

28. (new) The slurry of claim 23, wherein the slurry has a pH in the range of from 8.5 to 9.5.